

SOT713-1

plastic thin fine-pitch ball grid array package; 204 balls; body
11 x 11 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA204
Package type industry code	TFBGA204
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	23-6-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.9	-	11	11.1	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	1.12	1.12	mm
A ₂	package height	0.76	-	0.8	0.84	mm
n ₂	actual quantity of termination	-	-	204	-	



2. Package outline

TFBGA204: plastic thin fine-pitch ball grid array package; 204 balls; body 11 x 11 x 0.8 mm SOT713-1

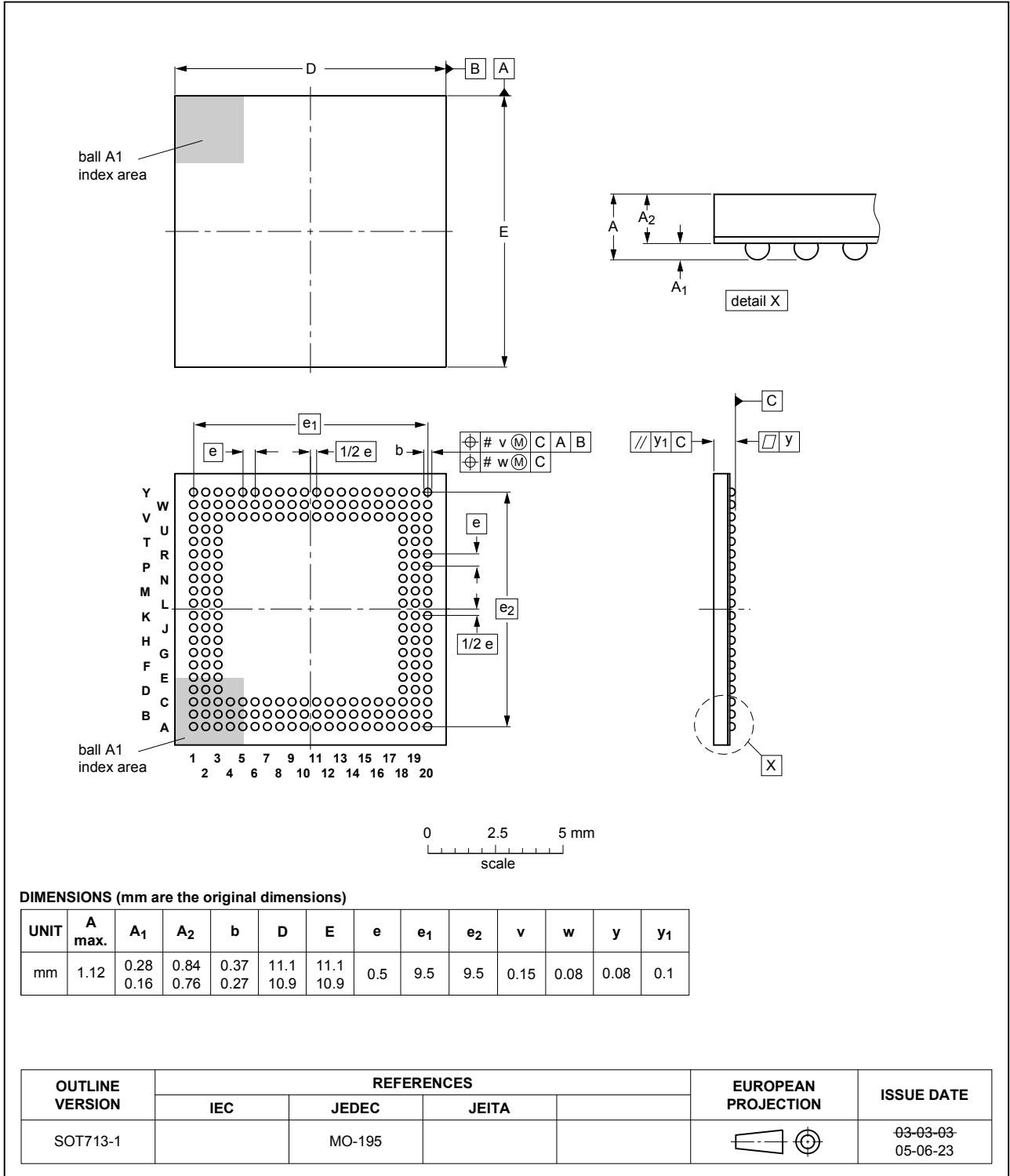


Fig. 1. Package outline TFBGA204 (SOT713-1)

3. Soldering

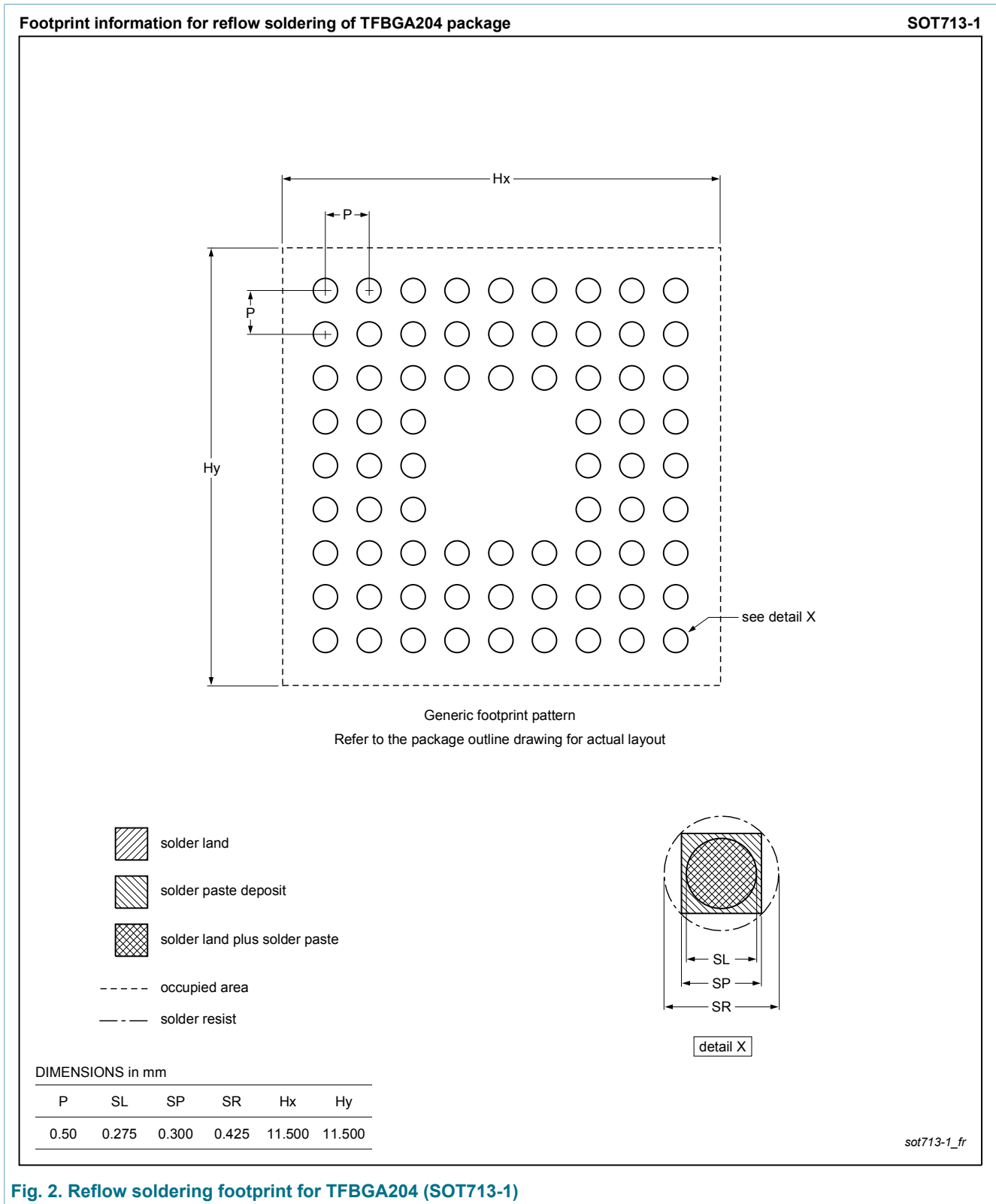


Fig. 2. Reflow soldering footprint for TFBGA204 (SOT713-1)

4. Legal information

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